# DARF N MLCC

### CONTENT (MLCC)

E STANDARD NUMBER	3
STRUCTURE	4
ORDERING CODE	
HIGH O & LOW ESR TYPE (O SERIES)	
TEST SPEC.	
PACKAGE	12
OTHERS	14

### E Standard Number

E3	1.0							2	.2				4.7											
E6		1.	.0			1	.5			2	.2			3	.3			4	.7			6	.8	
E12	1.	0	1.	2	1.	.5	1	.8	2	.2	2	.7	3.	.3	3	.9	4	.7	5.	.6	6.	.8	8	.2
E24	1.0	1.1	1.2	1.3	1.5	1.6	1.8	2.0	2.2	2.4	2.7	3.0	3.3	3.6	3.9	4.3	4.7	5.1	5.6	6.2	6.8	7.5	8.2	9.1

MLCC

Rev. 202407-1

Structure         (I)
(A)Kicke Inner Electrode (Ni) (B)Ceramic (Ceramic powder) (B)SI :: BBTOB (C)Ceramication Kiddle Layer (Ni) (B)Ceramication Kiddle Layer (Ni) (B)Ceramic
Ordering Code         C 1005 NP0 101 J G T Q           PRODUCT CODE
$\begin{array}{l c c c c c c c c c c c c c c c c c c c$
$C = MLCC$ SIZE in mm (EIA CODE, in inch) $\begin{array}{c} 0402(01005) & 0603(0201) & 1005 (0402) & 1608 (0603) & 2012 (0805) \\ 3216 (1206) & 3225(1210) & 4520 (1808) & 4532 (1812) \end{array}$ T. C. $\begin{array}{c} NP0: \ 0 \pm 30ppm/^{\circ}C & -55^{\circ}C \ to \pm 125^{\circ}C \\ X7R: \pm 15\% & -55^{\circ}C \ to \pm 125^{\circ}C \\ X5R: \pm 15\% & -55^{\circ}C \ to \pm 85^{\circ}C \\ Y5V: \pm 22\%/-82\% & -30^{\circ}C \ to \pm 85^{\circ}C \\ \end{array}$
$\begin{array}{c} \text{SIZE in mm (EIA CODE, in inch)} \\ & 0402(01005) & 0603(0201) & 1005 (0402) & 1608 (0603) & 2012 (0805) \\ & 3216 (1206) & 3225(1210) & 4520 (1808) & 4532 (1812) \\ \hline \textbf{T. C.} \\ & \text{NP0: } 0 \pm 30 \text{ppm/}^{\circ} \begin{tabular}{lllllllllllllllllllllllllllllllllll$
T. C.
Examples:
Everyoped in pice forede and identified by a three digit number
First two digits represent significant figures.
Last digit specifies the number of zeros.
(Use 9 for 1.0 through 9.9pF; Use 8 for 0.20 through 0.99pF) <u>101 100</u>
A: ± 0.05pF       B: ± 0.1pF       C: ± 0.25pF       D: ± 0.5pF       F: ±1%       G: ±2%         J: ±5%       K: ±10%       M: ±20%       Z: +80/-20%
B: 4V C: 6.3V D: 10V E: 16V F: 25V N: 35V G: 50V H: 100V J: 200V K: 250V L: 500V M: 630V P: 1KV Q: 2KV R: 3KV S: 4KV
T: Paper tape reel Ø180mm (7")       P: Embossed tape reel Ø180mm (7")         N: Paper tape reel Ø250mm (10")       D: Embossed tape reel Ø250mm (10")         A: Paper tape reel Ø330mm (13")       E: Embossed tape reel Ø330mm (13")         W: Special Packing       Application Code

## DARF<sup>®</sup>N

### High Q & Low ESR Type (Q Series)

#### Feature

- 1. Ultra-stable
- 2. Tight tolerance available
- $3. \quad Low \ ESR \ (Frequency \ is \ within \ 2.4GHz)$
- 4. Good frequency performance
- 5. No aging of capacitance
- 6. RoHS compliant
- 7. Halogen Free

Standard External Dimensions



TYPE	Dimension (mm)										
(EIA Size)	L (Length)	W (Width)	T (Max.)	g (Min)	A (Min/Max)						
C0603 (0201)	0.6±0.03	0.3±0.03	0.33	0.15	0.10/0.20						
C1005 (0402)	1.0 ± 0.05	0.5 ± 0.05	0.55	0.30	0.15/0.35						
C1608 (0603)	1.6 ± 0.10	0.8 ± 0.10	0.90	0.50	0.25/0.65						

### Part Number & Characteristic

### C0603NP0\_Q Series (EIA0201)

	DADEON D/N	Measuring	Capaci	tance		Thick.	Toleran	ce(mm)	Testing	ESR	Q	Standard
RV	DARFON P/N	Condition	Value	Unit	Available Tolerance	(mm)	L/W	Thick.	Freq	mΩ (max)	(min.)	Packing
4001/	C0603NP0229□HTQ	1V, 1MHz	2.2	pF	±0.25pF, ±0.1pF	0.30	±0.03	±0.03	1GHz	289	250	
1000	C0603NP0339□HTQ	1V, 1MHz	3.3	pF	±0.25pF, ±0.1pF	0.30	±0.03	±0.03	1GHz	241	200	Paper, 15Kpcs
	C0603NP0108CGTQ	1V, 1MHz	0.1	pF	±0.25pF	0.30	±0.03	±0.03	1GHz	4547	350	
	C0603NP0208□GTQ	1V, 1MHz	0.2	pF	±0.25pF, ±0.1pF, ±0.05pF	0.30	±0.03	±0.03	1GHz	2274	350	
	C0603NP0308□GTQ	1V, 1MHz	0.3	pF	±0.25pF, ±0.1pF, ±0.05pF	0.30	±0.03	±0.03	1GHz	1516	350	
	C0603NP0408□GTQ	1V, 1MHz	0.4	pF	±0.25pF, ±0.1pF, ±0.05pF	0.30	±0.03	±0.03	1GHz	1137	350	
	C0603NP0508□GTQ	1V, 1MHz	0.5	pF	±0.25pF, ±0.1pF, ±0.05pF	0.30	±0.03	±0.03	1GHz	909	350	
	C0603NP0608□GTQ	1V, 1MHz	0.6	pF	±0.25pF, ±0.1pF, ±0.05pF	0.30	±0.03	±0.03	1GHz	758	350	
	C0603NP0708□GTQ	1V, 1MHz	0.7	pF	±0.25pF, ±0.1pF, ±0.05pF	0.30	±0.03	±0.03	1GHz	650	350	
	C0603NP0758□GTQ	1V, 1MHz	0.75	pF	±0.25pF, ±0.1pF, ±0.05pF	0.30	±0.03	±0.03	1GHz	606	350	
	C0603NP0808□GTQ	1V, 1MHz	0.8	pF	±0.25pF, ±0.1pF, ±0.05pF	0.30	±0.03	±0.03	1GHz	568	350	
	C0603NP0908□GTQ	1V, 1MHz	0.9	pF	±0.25pF, ±0.1pF, ±0.05pF	0.30	±0.03	±0.03	1GHz	505	350	
	C0603NP0109□GTQ	1V, 1MHz	1.0	pF	±0.25pF, ±0.1pF, ±0.05pF	0.30	±0.03	±0.03	1GHz	455	350	
	C0603NP0119□GTQ	1V, 1MHz	1.1	pF	±0.25pF, ±0.1pF, ±0.05pF	0.30	±0.03	±0.03	1GHz	482	300	
	C0603NP0129□GTQ	1V, 1MHz	1.2	pF	±0.25pF, ±0.1pF, ±0.05pF	0.30	±0.03	±0.03	1GHz	442	300	
	C0603NP0139□GTQ	1V, 1MHz	1.3	pF	±0.25pF, ±0.1pF, ±0.05pF	0.30	±0.03	±0.03	1GHz	408	300	
	C0603NP0149□GTQ	1V, 1MHz	1.4	pF	±0.25pF, ±0.1pF, ±0.05pF	0.30	±0.03	±0.03	1GHz	379	300	
50V	C0603NP0159□GTQ	1V, 1MHz	1.5	pF	±0.25pF, ±0.1pF, ±0.05pF	0.30	±0.03	±0.03	1GHz	354	300	Paper, 15Kpcs
	C0603NP0169□GTQ	1V, 1MHz	1.6	pF	±0.25pF, ±0.1pF, ±0.05pF	0.30	±0.03	±0.03	1GHz	332	300	
	C0603NP0179□GTQ	1V, 1MHz	1.7	pF	±0.25pF, ±0.1pF, ±0.05pF	0.30	±0.03	±0.03	1GHz	312	300	
	C0603NP0189□GTQ	1V, 1MHz	1.8	pF	±0.25pF, ±0.1pF, ±0.05pF	0.30	±0.03	±0.03	1GHz	295	300	
	C0603NP0209□GTQ	1V, 1MHz	2.0	pF	±0.25pF, ±0.1pF, ±0.05pF	0.30	±0.03	±0.03	1GHz	318	250	
	C0603NP0229□GTQ	1V, 1MHz	2.2	pF	±0.25pF, ±0.1pF, ±0.05pF	0.30	±0.03	±0.03	1GHz	289	250	
	C0603NP0249□GTQ	1V, 1MHz	2.4	pF	±0.25pF, ±0.1pF, ±0.05pF	0.30	±0.03	±0.03	1GHz	265	250	
	C0603NP0259□GTQ	1V, 1MHz	2.5	pF	±0.25pF, ±0.1pF, ±0.05pF	0.30	±0.03	±0.03	1GHz	255	250	
	C0603NP0279□GTQ	1V, 1MHz	2.7	pF	±0.25pF, ±0.1pF, ±0.05pF	0.30	±0.03	±0.03	1GHz	236	250	
	C0603NP0309□GTQ	1V, 1MHz	3.0	pF	±0.25pF, ±0.1pF, ±0.05pF	0.30	±0.03	±0.03	1GHz	265	200	
	C0603NP0339□GTQ	1V, 1MHz	3.3	pF	±0.25pF, ±0.1pF, ±0.05pF	0.30	±0.03	±0.03	1GHz	241	200	
	C0603NP0369□GTQ	1V, 1MHz	3.6	pF	±0.25pF, ±0.1pF, ±0.05pF	0.30	±0.03	±0.03	1GHz	221	200	
	C0603NP0399□GTQ	1V, 1MHz	3.9	pF	±0.25pF, ±0.1pF, ±0.05pF	0.30	±0.03	±0.03	1GHz	204	200	
	C0603NP0409CGTQ	1V, 1MHz	4.0	pF	±0.25pF	0.30	±0.03	±0.03	1GHz	199	200	
	C0603NP0439□GTQ	1V, 1MHz	4.3	pF	±0.25pF, ±0.1pF, ±0.05pF	0.30	±0.03	±0.03	1GHz	185	200	
	C0603NP0479□GTQ	1V, 1MHz	4.7	pF	±0.25pF, ±0.1pF, ±0.05pF	0.30	±0.03	±0.03	1GHz	169	200	

### Application

- 1. LC and RC tuned circuit
- 2. Filtering
- 3. Timing

BV		Measuring	Capaci	tance	Available Telerance	Thick.	Tolerar	ce(mm)	Testing	ESR	Q	Standard
ĸv	DARFON P/N	Condition	Value	Unit	Available Tolerance	(mm)	L/W	Thick.	Freq	(max.)	(min.)	Packing
	C0603NP0509□GTQ	1V, 1MHz	5.0	pF	±0.5pF, ±0.25pF, ±0.1pF	0.30	±0.03	±0.03	1GHz	177	180	
	C0603NP0519□GTQ	1V, 1MHz	5.1	pF	±0.5pF, ±0.25pF, ±0.1pF	0.30	±0.03	±0.03	1GHz	173	180	
	C0603NP0569□GTQ	1V, 1MHz	5.6	pF	±0.5pF, ±0.25pF, ±0.1pF	0.30	±0.03	±0.03	1GHz	158	180	
		1V, 1MHz	6.0	p⊦	±0.5pF, ±0.25pF, ±0.1pF	0.30	±0.03	±0.03	1GHz	147	180	
		1V, 1MHz	6.8	pr pF	$\pm 0.5 \mu$ F, $\pm 0.25 \mu$ F, $\pm 0.1 \mu$ F	0.30	±0.03	±0.03	1GHz	143	180	
	C0603NP0709□GTQ	1V, 1MHz	7.0	pF	±0.5pF, ±0.25pF, ±0.1pF	0.30	±0.03	±0.03	1GHz	189	120	
	C0603NP0759□GTQ	1V, 1MHz	7.5	pF	±0.5pF, ±0.25pF, ±0.1pF	0.30	±0.03	±0.03	1GHz	177	120	
	C0603NP0809□GTQ	1V, 1MHz	8.0	pF	±0.5pF, ±0.25pF, ±0.1pF	0.30	±0.03	±0.03	1GHz	166	120	
	C0603NP0829□GTQ	1V, 1MHz	8.2	pF	±0.5pF, ±0.25pF, ±0.1pF	0.30	±0.03	±0.03	1GHz	162	120	
50V	C0603NP0909□GTQ	1V, 1MHz	9.0	pF	±0.5pF, ±0.25pF, ±0.1pF	0.30	±0.03	±0.03	1GHz	147	120	Paper, 15Kpcs
	C0603NP0919 GTQ	1V, 1MHz	9.1	pF	±0.5pF, ±0.25pF, ±0.1pF	0.30	±0.03	±0.03	1GHz	146	120	
		1V, 1MHz	10	p⊢	±5%, ±2%	0.30	±0.03	±0.03	1GHz	133	120	
	C0603NP0120CGTQ	1V, 1MHz	12	pF pF	±5%, ±2%	0.30	±0.03	$\pm 0.03$	1GHz	130	90	
	C0603NP0130□GTQ	1V, 1MHz	13	pF	±5%, ±2%	0.30	+0.03	±0.03	1GHz	153	80	
	C0603NP0150 GTQ	1V, 1MHz	15	pF	±5%, ±2%	0.30	±0.03	±0.03	1GHz	152	70	
	C0603NP0160□GTQ	1V, 1MHz	16	pF	±5%, ±2%	0.30	±0.03	±0.03	1GHz	166	60	
	C0603NP0180□GTQ	1V, 1MHz	18	pF	±5%, ±2%	0.30	±0.03	±0.03	1GHz	147	60	
	C0603NP0200□GTQ	1V, 1MHz	20	pF	±5%, ±2%	0.30	±0.03	±0.03	1GHz	199	40	
	C0603NP0220□GTQ	1V, 1MHz	22	pF	±5%,±2%,±1%	0.30	±0.03	±0.03	1GHz	207	35	
		1V, 1MHz	0.1	p⊦	±0.25pF, ±0.1pF, ±0.05pF	0.30	±0.03	±0.03	1GHz	4547	350	
		1V, 1MHz	0.2	pF nF	±0.25pF, ±0.1pF, ±0.05pF	0.30	±0.03	±0.03	1GHz	1516	350	
	C0603NP0408□FTQ	1V 1MHz	0.3	pF pF	±0.25pF, ±0.1pF, ±0.05pF ±0.25pF ±0.1pF ±0.05pF	0.30	+0.03	+0.03	1GHz	1137	350	
	C0603NP0508□FTQ	1V. 1MHz	0.5	pF	±0.25pF, ±0.1pF, ±0.05pF	0.30	±0.03	±0.00	1GHz	909	350	
	C0603NP0608□FTQ	1V, 1MHz	0.6	pF	±0.25pF, ±0.1pF, ±0.05pF	0.30	±0.03	±0.03	1GHz	758	350	
	C0603NP0708□FTQ	1V, 1MHz	0.7	pF	±0.25pF, ±0.1pF, ±0.05pF	0.30	±0.03	±0.03	1GHz	650	350	
	C0603NP0758□FTQ	1V, 1MHz	0.75	pF	±0.25pF, ±0.1pF, ±0.05pF	0.30	±0.03	±0.03	1GHz	606	350	
	C0603NP0808□FTQ	1V, 1MHz	0.8	pF	±0.25pF, ±0.1pF, ±0.05pF	0.30	±0.03	±0.03	1GHz	568	350	
	C0603NP0908 FTQ	1V, 1MHz	0.9	pF	±0.25pF, ±0.1pF, ±0.05pF	0.30	±0.03	±0.03	1GHz	505	350	
		1V, 1MHz	1.0	p⊦	±0.25pF, ±0.1pF, ±0.05pF	0.30	±0.03	±0.03	1GHz	455	350	
		1V, 1MHz	1.1	pr pF	±0.25pF, ±0.1pF, ±0.05pF ±0.25pF ±0.1pF ±0.05pF	0.30	±0.03	±0.03	1GHz	482	300	
	C0603NP0139□FTQ	1V, 1MHz	1.2	pF	±0.25pF, ±0.1pF, ±0.05pF	0.30	+0.03	±0.03	1GHz	408	300	
	C0603NP0149□FTQ	1V, 1MHz	1.4	pF	±0.25pF, ±0.1pF, ±0.05pF	0.30	±0.03	±0.03	1GHz	379	300	
	C0603NP0159□FTQ	1V, 1MHz	1.5	pF	±0.25pF, ±0.1pF, ±0.05pF	0.30	±0.03	±0.03	1GHz	354	300	
	C0603NP0169□FTQ	1V, 1MHz	1.6	pF	±0.25pF, ±0.1pF, ±0.05pF	0.30	±0.03	±0.03	1GHz	332	300	
	C0603NP0189□FTQ	1V, 1MHz	1.8	pF	±0.25pF, ±0.1pF, ±0.05pF	0.30	±0.03	±0.03	1GHz	295	300	
	C0603NP0209□FTQ	1V, 1MHz	2.0	pF	±0.25pF, ±0.1pF, ±0.05pF	0.30	±0.03	±0.03	1GHz	318	250	
		1V, 1MHz	2.2	p⊢	±0.25pF, ±0.1pF, ±0.05pF	0.30	±0.03	±0.03	1GHz	289	250	
		1V, 1MHz	2.4	pr pF	±0.25pF, ±0.1pF, ±0.05pF ±0.25pF ±0.1pF ±0.05pF	0.30	±0.03	±0.03	1GHz	265	250	
	C0603NP0279□FTQ	1V, 1MHz	2.7	pF	±0.25pF, ±0.1pF, ±0.05pF	0.30	+0.03	±0.03	1GHz	236	250	
	C0603NP0309□FTQ	1V, 1MHz	3.0	pF	±0.25pF, ±0.1pF, ±0.05pF	0.30	±0.03	±0.03	1GHz	265	200	
	C0603NP0339□FTQ	1V, 1MHz	3.3	pF	±0.25pF, ±0.1pF, ±0.05pF	0.30	±0.03	±0.03	1GHz	241	200	
25V	C0603NP0369□FTQ	1V, 1MHz	3.6	pF	±0.25pF, ±0.1pF, ±0.05pF	0.30	±0.03	±0.03	1GHz	221	200	Paper, 15Kpcs
	C0603NP0399□FTQ	1V, 1MHz	3.9	pF	±0.25pF, ±0.1pF, ±0.05pF	0.30	±0.03	±0.03	1GHz	204	200	
	C0603NP0409□FTQ	1V, 1MHz	4.0	pF	±0.25pF, ±0.1pF, ±0.05pF	0.30	±0.03	±0.03	1GHz	199	200	
		1V, 1MHz	4.3	p⊢	±0.25pF, ±0.1pF, ±0.05pF	0.30	±0.03	±0.03	1GHz	185	200	
		1V, 1MHz	4.7	pF	$\pm 0.25$ pF, $\pm 0.1$ pF, $\pm 0.05$ pF	0.30	±0.03	±0.03	1GHz	109	200	
	C0603NP0519□FTQ	1V 1MHz	5.0	pF	+0.5pF +0.25pF +0.1pF	0.30	+0.03	+0.03	1GHz	173	180	
	C0603NP0569□FTQ	1V, 1MHz	5.6	pF	±0.5pF, ±0.25pF, ±0.1pF	0.30	±0.03	±0.03	1GHz	158	180	
	C0603NP0609□FTQ	1V, 1MHz	6.0	pF	±0.5pF, ±0.25pF, ±0.1pF	0.30	±0.03	±0.03	1GHz	147	180	
	C0603NP0629□FTQ	1V, 1MHz	6.2	pF	±0.5pF, ±0.25pF, ±0.1pF	0.30	±0.03	±0.03	1GHz	143	180	
	C0603NP0689□FTQ	1V, 1MHz	6.8	pF	±0.5pF, ±0.25pF, ±0.1pF	0.30	±0.03	±0.03	1GHz	130	180	
	C0603NP0709□FTQ	1V, 1MHz	7.0	pF	±0.5pF, ±0.25pF, ±0.1pF	0.30	±0.03	±0.03	1GHz	189	120	
		1V, 1MHz	7.5	p⊦	±0.5pF, ±0.25pF, ±0.1pF	0.30	±0.03	±0.03	1GHz	177	120	
		1V, 1MHz	9.0	pr pF	$\pm 0.5 \mu$ F, $\pm 0.25 \mu$ F, $\pm 0.1 \mu$ F	0.30	±0.03	±0.03	1GHz	102	120	
	C0603NP0919□FTQ	1V, 1MHz	9.1	pF	±0.5pF, ±0.25pF, ±0.1pF	0.30	+0.03	±0.03	1GHz	146	120	
	C0603NP0959□FTQ	1V, 1MHz	9.5	pF	±0.5pF, ±0.25pF, ±0.1pF	0.30	±0.03	±0.03	1GHz	140	120	
	C0603NP0100□FTQ	1V, 1MHz	10	pF	±5%, ±2%	0.30	±0.03	±0.03	1GHz	133	120	
	C0603NP0110□FTQ	1V, 1MHz	11	pF	±5%, ±2%	0.30	±0.03	±0.03	1GHz	138	105	
	C0603NP0120□FTQ	1V, 1MHz	12	pF	±5%, ±2%	0.30	±0.03	±0.03	1GHz	147	90	
	C0603NP0130 FTQ	1V, 1MHz	13	pF	±5%, ±2%	0.30	±0.03	±0.03	1GHz	153	80	
		1V, 1MHz	15	pF	±5%, ±2%	0.30	±0.03	±0.03	1GHz	152	70	
		1V, 1MH7	10	ρF nF	±0%, ±2% +5% +2%	0.30	±0.03	±0.03	1687	147	00	
	C0603NP0200	1V. 1MH7	20	pF	±5%. ±2%	0.30	±0.03	±0.03	1GH7	199	40	
	C0603NP0220□FTQ	1V, 1MHz	22	pF	±5%,±2%,±1%	0.30	±0.03	±0.03	1GHz	207	35	

□ Tolerance Code: A=±0.05 pF, B=±0.1pF, C=±0.25pF ,D=±0.5pF, G=±2%, J=±5%; Special tolerance on the request.

### • C1005NP0\_Q Series (EIA0402)

-	DADEON DAL	Measuring	Capaci	tance		Thick.	Tolerar	nce(mm)	Testing	ESR	Q	Standard		
RV	DARFON P/N	Condition	Value	Unit	Available Tolerance	(mm)	L/W	Thick.	Freq	mΩ (max)	(min.)	Packing		
	C1005NP0308□HTQ	1V, 1MHz	0.3	pF	±0.25pF, ±0.1pF, ±0.05pF	0.50	±0.05	±0.05	1GHz	1768	300			
100V	C1005NP0109□HTQ	1V, 1MHz	1.0	pF	±0.25pF,±0.1pF,±0.05pF	0.50	±0.05	±0.05	1GHz	531	300	Paper, 10Kpcs		
	C1005NP0108BGTQ	1V, 1MHz	0.1	pF	±0.1pF	0.50	±0.05	±0.05	1GHz	5305	300			
	C1005NP0208□GTQ	1V, 1MHz	0.2	pF	±0.25pF, ±0.1pF, ±0.05pF	0.50	±0.05	±0.05	1GHz	2653	300			
	C1005NP0308□GTQ	1V, 1MHz	0.3	pF	±0.25pF, ±0.1pF, ±0.05pF	0.50	±0.05	±0.05	1GHz	1768	300			
	C1005NP0408□GTQ	1V, 1MHz	0.4	pF	±0.25pF, ±0.1pF, ±0.05pF	0.50	±0.05	±0.05	1GHz	1326	300			
	C1005NP0508□GTQ	1V, 1MHz	0.5	pF	±0.25pF, ±0.1pF, ±0.05pF	0.50	±0.05	±0.05	1GHz	1061	300			
	C1005NP0568□GTQ	1V, 1MHz	0.56	pF	±0.25pF, ±0.1pF, ±0.05pF	0.50	±0.05	±0.05	1GHz	947	300			
	C1005NP0608□GTQ	1V, 1MHz	0.6	pF	±0.25pF, ±0.1pF, ±0.05pF	0.50	±0.05	±0.05	1GHz	884	300			
	C1005NP0708□GTQ	1V, 1MHz	0.7	pF	±0.25pF, ±0.1pF, ±0.05pF	0.50	±0.05	±0.05	1GHz	758	300			
	C1005NP0758□GTQ	1V, 1MHz	0.75	pF	±0.25pF, ±0.1pF, ±0.05pF	0.50	±0.05	±0.05	1GHz	707	300			
	C1005NP0808□GTQ	1V, 1MHz	0.8	pF	±0.25pF, ±0.1pF, ±0.05pF	0.50	±0.05	±0.05	1GHz	663	300			
	C1005NP0828□GTQ	1V, 1MHz	0.82	pF	±0.25pF, ±0.1pF, ±0.05pF	0.50	±0.05	±0.05	1GHz	647	300			
	C1005NP0908□GTQ	1V, 1MHz	0.9	pF	±0.25pF, ±0.1pF, ±0.05pF	0.50	±0.05	±0.05	1GHz	589	300			
	C1005NP0109□GTQ	1V, 1MHz	1.0	pF	±0.25pF, ±0.1pF, ±0.05pF	0.50	±0.05	±0.05	1GHz	531	300			
	C1005NP0119□GTQ	1V, 1MHz	1.1	pF	±0.25pF, ±0.1pF, ±0.05pF	0.50	±0.05	±0.05	1GHz	482	300			
	C1005NP0129□GTQ	1V, 1MHz	1.2	pF	±0.25pF, ±0.1pF, ±0.05pF	0.50	±0.05	±0.05	1GHz	531	250			
	C1005NP0139□GTQ	1V, 1MHz	1.3	pF	±0.25pF, ±0.1pF, ±0.05pF	0.50	±0.05	±0.05	1GHz	490	250			
	C1005NP0159□GTQ	1V, 1MHz	1.5	pF	±0.25pF, ±0.1pF, ±0.05pF	0.50	±0.05	±0.05	1GHz	424	250			
	C1005NP0169□GTQ	1V, 1MHz	1.6	pF	±0.25pF, ±0.1pF, ±0.05pF	0.50	±0.05	±0.05	1GHz	398	250			
	C1005NP0189LIGTQ	1V, 1MHz	1.8	p⊦	±0.25pF, ±0.1pF, ±0.05pF	0.50	±0.05	±0.05	1GHz	354	250			
	C1005NP0209LIGTQ	1V, 1MHz	2.0	p⊦	±0.25pF, ±0.1pF, ±0.05pF	0.50	±0.05	±0.05	1GHz	398	200			
		1V, 1MHz	2.2	p⊦	±0.25pF, ±0.1pF, ±0.05pF	0.50	±0.05	±0.05	1GHz	362	200			
		1V, 1MHZ	2.4	p⊢ 	±0.25pF, ±0.1pF, ±0.05pF	0.50	±0.05	±0.05	1GHZ	332	200			
		1V, 1MHZ	2.5	p⊢	±0.25pF, ±0.1pF	0.50	±0.05	±0.05	1GHZ	318	200			
			2.7	pr ~	±0.25pF, ±0.1pF, ±0.05pF	0.50	±0.05	±0.05		295	200			
			2.9	pr ~	±0.25pF, ±0.1pF, ±0.05pF	0.50	±0.05	±0.05		274	200			
501/			3.0	рг	±0.25pF, ±0.1pF, ±0.05pF	0.50	±0.05	±0.05		200	200	Dopor 10Knoo		
500			3.3	рг	±0.25pF, ±0.1pF, ±0.05pF	0.50	±0.05	±0.05		241	200	Paper, 10Kpcs		
			3.0	pr nE	$\pm 0.25pF$ , $\pm 0.1pF$ , $\pm 0.05pF$	0.50	±0.05	±0.05		240	100			
		1V, 1MHz	3.9	pF pF	$\pm 0.25pF$ , $\pm 0.1pF$ , $\pm 0.05pF$	0.50	±0.05	±0.05	1GHz	221	180			
	C1005NP0439CGTQ	1V, 1MHz	4.0	pi pF	+0.25pF +0.1pF	0.50	bu         ±0.05         ±0.05         1GHz         221           50         ±0.05         ±0.05         10Hz         200		180					
	C1005NP0479CGTQ	1V, 1MHz	4.3	pi pF	+0.25pF +0.1pF +0.05pF	SpF, ±0.1pF         0.50         ±0.05         ±0.05         1GHz         206           ±0.1pE         ±0.05E         ±0.05 <td< td=""><td>180</td><td></td></td<>		180						
		1V 1MHz	5.0	nF	+0.5pF +0.25pF +0.1pF	0.50	+0.05	+0.05	1GHz	212	150			
	C1005NP0519□GT0	1V 1MHz	5.0	nF	+0.5pF +0.25pF +0.1pF	0.50	+0.05	+0.05	1GHz	208	150			
	C1005NP0569□GTQ	1V 1MHz	5.6	p. pF	+0.5pF +0.25pF +0.1pF	0.50	+0.05	+0.05	1GHz	189	150			
	C1005NP0609□GTQ	1V. 1MHz	6.0	pF	±0.5pF, ±0.25pF, ±0.1pF	0.50	+0.05	+0.05	1GHz	177	150			
	C1005NP0629□GTQ	1V. 1MHz	6.2	pF	±0.5pF, ±0.25pF, ±0.1pF	0.50	±0.05	±0.05	1GHz	171	150			
	C1005NP0689□GTQ	1V. 1MHz	6.8	pF	±0.5pF, ±0.25pF, ±0.1pF	0.50	±0.05	±0.05	1GHz	156	150			
	C1005NP0709□GTQ	1V, 1MHz	7.0	pF	±0.5pF, ±0.25pF, ±0.1pF	0.50	±0.05	±0.05	1GHz	227	100			
	C1005NP0759□GTQ	1V, 1MHz	7.5	pF	±0.5pF, ±0.25pF, ±0.1pF	0.50	±0.05	±0.05	1GHz	212	100			
	C1005NP0809□GTQ	1V, 1MHz	8.0	pF	±0.5pF, ±0.25pF, ±0.1pF	0.50	±0.05	±0.05	1GHz	199	100			
	C1005NP0829□GTQ	1V, 1MHz	8.2	pF	±0.5pF, ±0.25pF, ±0.1pF	0.50	±0.05	±0.05	1GHz	194	100			
	C1005NP0909□GTQ	1V, 1MHz	9.0	pF	±0.5pF, ±0.25pF, ±0.1pF	0.50	±0.05	±0.05	1GHz	177	100			
	C1005NP0919□GTQ	1V, 1MHz	9.1	pF	±0.5pF, ±0.25pF, ±0.1pF	0.50	±0.05	±0.05	1GHz	175	100			
	C1005NP0959□GTQ	1V, 1MHz	9.5	pF	±0.5pF, ±0.25pF, ±0.1pF	0.50	±0.05	±0.05	1GHz	186	90			
	C1005NP0100□GTQ	1V, 1MHz	10	pF	±5%, ±2%, ±1%	0.50	±0.05	±0.05	1GHz	199	80			
	C1005NP0110□GTQ	1V, 1MHz	11	pF	±5%, ±2%	0.50	±0.05	±0.05	1GHz	207	70			
	C1005NP0120□GTQ	1V, 1MHz	12	pF	±5%, ±2%	0.50	±0.05	±0.05	1GHz	221	60			
	C1005NP0150□GTQ	1V, 1MHz	15	pF	±5%, ±2%, ±1%	0.50	±0.05	±0.05	1GHz	265	40			
	C1005NP0160□GTQ	1V, 1MHz	16	pF	±5%, ±2%, ±1%	0.50	±0.05	±0.05	1GHz	284	35			
	C1005NP0180□GTQ	1V, 1MHz	18	pF	±5%, ±2%, ±1%	0.50	±0.05	±0.05	1GHz	295	30			
	C1005NP0200□GTQ	1V, 1MHz	20	pF	±5%, ±2%	0.50	±0.05	±0.05	1GHz	398	20			
	C1005NP0220 GTQ	1V, 1MHz	22	pF	±5%, ±2%	0.50	±0.05	±0.05	1GHz	362	20			
	C1005NP0300 GTQ	1V, 1MHz	30	pF	±5%, ±2%	0.50	±0.05	±0.05	500MHz	295	18			
	C1005NP0330 GTQ	1V, 1MHz	33	pF	±5%, ±2%	0.50	±0.05	±0.05	500MHz	301	16			
	C1005NP0430 GTQ	1V, 1MHz	43	pF	±5%, ±2%	0.50	±0.05	±0.05	500MHz	264	14			
	C1005NP0470 GTQ	1V, 1MHz	47	pF	±5%, ±2%	0.50	±0.05	±0.05	500MHz	339	10			
	C1005NP0560 GTQ	1V, 1MHz	56	pF	±5%, ±2%	0.50	±0.05	±0.05	500MHz	316	9			
		1V, 1MHz	62	p⊦	±5%, ±2%	0.50	±0.05	±0.05	500MHz	321	8			
251/		IV, TIVIHZ	0.5	p⊢ p⊏	±0.1pF	0.50	±0.05	±0.05		1001	300	Dopor 10Knor		
ZOV		IV, INHZ	2.0	p⊢ r⊑	±0.1pr	0.50	±0.05	±0.05	1GHZ	398 100	200	Paper, TUKpcs		
161/		IV, IVIHZ	4./	pr	±0.20pr	0.50	±0.05	±0.05		100	100	Papar 10Knoc		
100	C TOUGINE O TOBDE TQ	I IV, HVI⊓Z	1.0	ιμг	±υ. ιμε	0.00	TO.03	TO.00		001	300	ι αρει, Ιυκρυδ		

□ Tolerance Code: A=±0.05 pF, B=±0.1pF, C=±0.25pF ,D=±0.5pF, G=±2%, J=±5%; Special tolerance on the request.

High Frequency Application

MLCC

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# DARFIN

### • C1608NP0\_Q Series (EIA0603)

-	DADEON DAL	Measuring	Capaci	tance		Thick.	Tolerar	ice(mm)	Testing	ESR	Q	Standard				
RV	DARFON P/N	Condition	Value	Unit	Available Tolerance	(mm)	L/W	Thick.	Freq	mΩ (max)	(min.)	Packing				
	C1608NP0308□KTQ	1V. 1MHz	0.3	рF	+0.25pF.+0.1pF.+0.05pF	0.80	±0.10	±0.10	1GHz	2122	250					
	C1608NP0408□KTQ	1V. 1MHz	0.4	pF	±0.25pF.±0.1pF.±0.05pF	0.80	±0.10	±0.10	1GHz	1592	250					
	C1608NP0508□KTQ	1V 1MHz	0.5	pF	+0.25pF +0.1pF +0.05pF	0.80	+0.10	+0.10	1GHz	1273	250					
	C1608NP0758□KTQ	1V 1MHz	0.75	pF	+0.25pF +0.1pF +0.05pF	0.80	+0.10	+0.10	1GHz	849	250					
	C1608NP0808□KTQ	1V. 1MHz	0.8	pF	±0.25pF.±0.1pF.±0.05pF	0.80	±0.10	±0.10	1GHz	796	250					
	C1608NP0109□KTQ	1V. 1MHz	1.0	pF	±0.25pF.±0.1pF.±0.05pF	0.80	±0.10	±0.10	1GHz	637	250					
	C1608NP0129□KTQ	1V 1MHz	12	pF	+0.25pF +0.1pF +0.05pF	0.80	+0.10	+0.10	1GHz	663	200					
	C1608NP0159□KTQ	1V 1MHz	1.5	pF	+0.25pF +0.1pF +0.05pF	0.80	+0.10	+0.10	1GHz	531	200					
	C1608NP0189□KTQ	1V 1MHz	1.8	pF	+0.25pF +0.1pF +0.05pF	0.80	+0.10	+0.10	1GHz	442	200					
	C1608NP0209	1V 1MHz	2.0	pF	+0.25pF +0.1pF +0.05pF	0.80	+0.10	+0.10	1GHz	531	150					
	C1608NP0229□KTQ	1V 1MHz	22	pF	+0.25pF +0.1pF +0.05pF	0.80	+0.10	+0.10	1GHz	482	150					
		1V 1MHz	24	p. pF	+0.25pF +0.1pF +0.05pF	0.80	+0.10	+0.10	1GHz	442	150					
		1V, 1MHz	2.4	nF	+0.25pF +0.1pF +0.05pF	0.00	+0.10	+0.10	1GHz	303	150					
		1V 1MHz	3.0	nF	+0.25pF +0.1pF +0.05pF	0.80	+0.10	+0.10	1GHz	531	100					
250V		1V 1MHz	3.3	p. pF	+0.25pF +0.1pF +0.05pF	0.80	+0.10	+0.10	1GHz	482	100	Paper, 4Kpcs				
		1V 1MHz	3.9	nF	+0.25pF +0.1pF +0.05pF	0.00	+0.10	+0.10	1GHz	408	100					
		1V 1MHz	47	p. pF	+0.25pF +0.1pF +0.05pF	0.80	+0.10	+0.10	1GHz	339	100					
	C1608NP0519□KTQ	1V 1MHz	5.1	pF	+0.25pF +0.1pF +0.05pF	0.80	+0.10	+0.10	1GHz	347	90					
		1V 1MHz	5.6	p. pF	+0.5pE +0.25pE +0.1pE	0.80	+0.10	+0.10	1GHz	355	80					
		1V 1MHz	6.0	p. pF	+0.5pF +0.25pF +0.1pF	0.80	+0.10	+0.10	1GHz	332	80					
	C1608NP0689□KTQ	1V 1MHz	6.8	pF	+0.5pE +0.25pE +0.1pE	0.80	+0.10	+0.10	1GHz	293	80					
		1V 1MHz	8.2	p. pF	+0.5pF +0.25pF +0.1pF	0.80	+0.10	+0.10	1GHz	277	70					
		1V, 1MHz	9.1	nF	+0.5pE +0.25pE +0.1pE	0.00	+0.10	+0.10	1GHz	250	70					
		1V, 1MHz	10	nF	+5% +2%	0.00	+0.10	+0.10	1GHz	200	70					
	C1608NP0120 IKTO	1V, 1MHz	10	nF	+5%	0.00	+0.10	+0.10	1GHz	332	40					
			12	pi nF	+5% +2%	0.00	±0.10	+0.10	10Hz	302	35					
			18	pi nF	+5% +2%	0.00	±0.10	+0.10	10Hz	205	30					
			22	pi nF	+5% +2%	0.00	±0.10	+0.10	10Hz	235	25					
		1V, 1MHz	0.2	pi nF	$\pm 0.25 \text{ pc} \pm 0.1 \text{ pc}$	0.00	±0.10	+0.10	1GHz	203	250					
	C1608NIP0120B ITO		1.2	pi nF	±0.25pi ,±0.1pi	0.00	10.10	+0.10	10Hz	663	200					
	C1600NP0129BJTQ		1.2	pr nE	±0.1pF	0.80	±0.10	±0.10		521	200					
			1.0	pr nE	±0.1pF	0.80	±0.10	±0.10		442	200					
		C1608NP0229BJTQ 1V, 1MHz 2.2 pF ±0.1pF 0.80 ±0.10 10 10 10								442	200					
			2.2	рг		0.80	±0.10	±0.10		402	150					
			2.4	pr ~	±0.25pF,±0.1pF, ±0.05pF	0.80	±0.10	±0.10		442	150					
2001/			2.7	рг	±0.1pF	0.80	±0.10	±0.10		593	100	Donor Alenon				
2000	C1608NP0309BJTQ		3.0	pr ~	±0.1pF	0.80	±0.10	±0.10		231	100	Paper, 4Kpcs				
	C1608NP0339BJTQ		3.3	pr ~	±0.1pF	0.80	±0.10	±0.10		482	100					
	C1608NP0399BJTQ	1V, 1MHZ	3.9	p⊢ 	±0.1pF	0.80	±0.10	±0.10	1GHZ	408	100					
	C1608NP0439BJTQ	1V, 1MHZ	4.3	p⊢ 	±0.1pF	0.80	±0.10	±0.10	1GHZ	370	100					
		C1608NP0479□JTQ 1V, 1MHz 4.7 pF ±0.25pF,±0.						±0.10	1GHZ	339	100					
		1V, 1MHZ	5.1	p⊢ 	±0.25pF,±0.1pF, ±0.05pF	0.80	±0.10	±0.10	1GHZ	347	90					
	C1608NP0689BJTQ	1V, 1MHZ	6.8	p⊢ 	±0.1pF	0.80	±0.10	±0.10	1GHZ	293	80					
	C1608NP0829CJTQ	1V, 1MHz	8.2	p⊦	±0.25pF	0.80	±0.10	±0.10	1GHz	2//	70					
		1V, 1MHz	0.3	p⊦	±0.25pF,±0.1pF, ±0.05pF	0.80	±0.10	±0.10	1GHz	2122	250					
	C1608NP0508LHIQ	1V, 1MHz	0.5	p⊦	±0.25pF,±0.1pF, ±0.05pF	0.80	±0.10	±0.10	1GHz	1273	250					
	C1608NP0758LHIQ	1V, 1MHz	0.75	p⊦	±0.25pF,±0.1pF, ±0.05pF	0.80	±0.10	±0.10	1GHz	849	250					
	C1608NP0109LHIQ	1V, 1MHz	1.0	p⊦	±0.25pF,±0.1pF, ±0.05pF	0.80	±0.10	±0.10	1GHz	637	250					
	C1608NP0129LHIQ	1V, 1MHz	1.2	p⊦	±0.25pF,±0.1pF, ±0.05pF	0.80	±0.10	±0.10	1GHz	663	200					
	C1608NP0159LHIQ	1V, 1MHz	1.5	p⊦	±0.25pF,±0.1pF, ±0.05pF	0.80	±0.10	±0.10	1GHz	531	200					
	C1608NP0189LHIQ	1V, 1MHz	1.8	p⊦	±0.25pF,±0.1pF, ±0.05pF	0.80	±0.10	±0.10	1GHz	442	200					
	C1608NP0209LHIQ	1V, 1MHz	2.0	p⊦	±0.25pF,±0.1pF, ±0.05pF	0.80	±0.10	±0.10	1GHz	531	150					
	C1608NP0229UHIQ	1V, 1MHz	2.2	p⊦	±0.25pF,±0.1pF, ±0.05pF	0.80	±0.10	±0.10	1GHz	482	150					
	C1608NP0249□HTQ	1V, 1MHz	2.4	pF	±0.25pF,±0.1pF, ±0.05pF	0.80	±0.10	±0.10	1GHz	442	150					
	C1608NP0279□HTQ	1V, 1MHz	2.7	pF	±0.25pF,±0.1pF, ±0.05pF	0.80	±0.10	±0.10	1GHz	393	150					
	C1608NP0309□HTQ	1V, 1MHz	3.0	pF	±0.25pF,±0.1pF, ±0.05pF	0.80	±0.10	±0.10	1GHz	531	100					
100V	C1608NP0339□HTQ	1V, 1MHz	3.3	pF	±0.25pF,±0.1pF, ±0.05pF	0.80	±0.10	±0.10	1GHz	482	100	Paper, 4Kpcs				
	C1608NP0399 HTQ	1V, 1MHz	3.9	pF	±0.25pF,±0.1pF, ±0.05pF	0.80	±0.10	±0.10	1GHz	408	100					
	C1608NP0479 HTQ	1V, 1MHz	4.7	pF	±0.25pF,±0.1pF, ±0.05pF	0.80	±0.10	±0.10	1GHz	339	100					
	C1608NP0509□HTQ	1V, 1MHz	5.0	pF	±0.25pF,±0.1pF	0.80	±0.10	±0.10	1GHz	354	90					
	C1608NP0569□HTQ	1V, 1MHz	5.6	pF	±0.5pF, ±0.25pF,±0.1pF	0.80	±0.10	±0.10	1GHz	355	80					
	C1608NP0609□HTQ	1V, 1MHz	6.0	pF	±0.5pF, ±0.25pF,±0.1pF	0.80	±0.10	±0.10	1GHz	332	80					
	C1608NP0689□HTQ	1V, 1MHz	6.8	pF	±0.5pF, ±0.25pF,±0.1pF	0.80	±0.10	±0.10	1GHz	293	80					
	C1608NP0829□HTQ	1V, 1MHz	8.2	pF	±0.5pF, ±0.25pF,±0.1pF	0.80	±0.10	±0.10	1GHz	277	70					
1	C1608NP0919□HTQ	1V, 1MHz	9.1	pF	±0.5pF, ±0.25pF,±0.1pF	0.80	±0.10	±0.10	1GHz	250	70					
	C1608NP0100JHTQ	1V, 1MHz	10	pF	±5%	0.80	±0.10	±0.10	1GHz	227	70					
1	C1608NP0120□HTQ	1V, 1MHz	12	pF	±5%,±2%,±1%	0.80	±0.10	±0.10	1GHz	332	40					
	C1608NP0150JHTQ	1V, 1MHz	15	pF	±5%	0.80	±0.10	±0.10	1GHz	303	35					
	C1608NP0180JHTQ	1V, 1MHz	18	pF	±5%	0.80	±0.10	±0.10	1GHz	295	30					
	C1608NP0220JHTQ	1V, 1MHz	22	pF	±5%	0.80	±0.10	±0.10	1GHz	289	25					

□ Tolerance Code: A=±0.05 pF, B=±0.1pF, C=±0.25pF ,D=±0.5pF, G=±2%, J=±5%; Special tolerance on the request.

DV		Measuring	Capaci	tance	Available Televenes	Thick.	Tolerar	nce(mm)	Testing	ESR	Q	Standard
ĸv	DARFON P/N	Condition	Value	Unit	Available Tolerance	(mm)	L/W	Thick.	Freq	(max)	(min.)	Packing
	C1608NP0208□GTQ	1V, 1MHz	0.20	pF	±0.25pF±0.1pF, ±0.05pF	0.80	±0.10	±0.10	1GHz	3183	250	
	C1608NP0228□GTQ	1V, 1MHz	0.22	pF	±0.25pF±0.1pF, ±0.05pF	0.80	±0.10	±0.10	1GHz	2894	250	
	C1608NP0308□GTQ	1V, 1MHz	0.30	pF	±0.25pF±0.1pF, ±0.05pF	0.80	±0.10	±0.10	1GHz	2122	250	
	C1608NP0508□GTQ	1V, 1MHz	0.50	pF	±0.25pF±0.1pF, ±0.05pF	0.80	±0.10	±0.10	1GHz	1273	250	
	C1608NP0758□GTQ	1V, 1MHz	0.75	pF	±0.25pF±0.1pF, ±0.05pF	0.80	±0.10	±0.10	1GHz	849	250	
	C1608NP0109□GTQ	1V, 1MHz	1.0	pF	±0.25pF±0.1pF, ±0.05pF	0.80	±0.10	±0.10	1GHz	637	250	
	C1608NP0129□GTQ	1V, 1MHz	1.2	pF	±0.25pF, ±0.1pF	0.80	±0.10	±0.10	1GHz	663	200	
	C1608NP0159□GTQ	1V, 1MHz	1.5	pF	±0.25pF, ±0.1pF	0.80	±0.10	±0.10	1GHz	531	200	
	C1608NP0189□GTQ	1V, 1MHz	1.8	pF	±0.25pF, ±0.1pF	0.80	±0.10	±0.10	1GHz	442	200	
	C1608NP0209□GTQ	1V, 1MHz	2.0	pF	±0.25pF, ±0.1pF	0.80	±0.10	±0.10	1GHz	531	150	
	C1608NP0229□GTQ	1V, 1MHz	2.2	pF	±0.25pF, ±0.1pF	0.80	±0.10	±0.10	1GHz	482	150	
	C1608NP0249□GTQ	1V, 1MHz	2.4	pF	±0.25pF, ±0.1pF	0.80	±0.10	±0.10	1GHz	442	150	
	C1608NP0279□GTQ	1V, 1MHz	2.7	pF	±0.25pF, ±0.1pF	0.80	±0.10	±0.10	1GHz	393	150	
501/	C1608NP0309□GTQ	1V, 1MHz	3.0	pF	±0.25pF, ±0.1pF	0.80	±0.10	±0.10	1GHz	531	100	Paper /Kncs
30 v	C1608NP0339□GTQ	1V, 1MHz	3.3	pF	±0.25pF, ±0.1pF	0.80	±0.10	±0.10	1GHz	482	100	Paper, 4Kpcs
	C1608NP0399□GTQ	1V, 1MHz	3.9	pF	±0.25pF, ±0.1pF	0.80	±0.10	±0.10	1GHz	408	100	
	C1608NP0479□GTQ	1V, 1MHz	4.7	pF	±0.25pF, ±0.1pF	0.80	±0.10	±0.10	1GHz	339	100	
	C1608NP0509□GTQ	1V, 1MHz	5.0	pF	±0.25pF, ±0.1pF	0.80	±0.10	±0.10	1GHz	354	90	
	C1608NP0569□GTQ	1V, 1MHz	5.6	pF	±0.5pF, ±0.25pF, ±0.1pF	0.80	±0.10	±0.10	1GHz	355	80	
	C1608NP0609□GTQ	1V, 1MHz	6.0	pF	±0.5pF, ±0.25pF, ±0.1pF	0.80	±0.10	±0.10	1GHz	332	80	
	C1608NP0689□GTQ	1V, 1MHz	6.8	pF	±0.5pF, ±0.25pF, ±0.1pF	0.80	±0.10	±0.10	1GHz	293	80	
	C1608NP0829□GTQ	1V, 1MHz	8.2	pF	±0.5pF, ±0.25pF, ±0.1pF	0.80	±0.10	±0.10	1GHz	277	70	
	C1608NP0919□GTQ	1V, 1MHz	9.1	pF	±0.5pF, ±0.25pF, ±0.1pF	0.80	±0.10	±0.10	1GHz	250	70	
	C1608NP0100JGTQ	1V, 1MHz	10	pF	±5%	0.80	±0.10	±0.10	1GHz	227	70	
	C1608NP0120□GTQ	1V, 1MHz	12	pF	±5%,±2%,±1%	0.80	±0.10	±0.10	1GHz	332	40	
	C1608NP0150JGTQ	1V, 1MHz	15	pF	±5%	0.80	±0.10	±0.10	1GHz	303	35	
	C1608NP0180JGTQ	1V, 1MHz	18	pF	±5%	0.80	±0.10	±0.10	1GHz	295	30	
	C1608NP0220JGTQ	1V, 1MHz	22	pF	±5%	0.80	±0.10	±0.10	1GHz	289	25	

on MLCC

### • Test Spec.

	lte	m	Specification	Test Method				
1	Operating Tempe	rature Range	NP0: -55 to 125 $^\circ\!\mathrm{C}$					
2	Rated Voltage		Shown in the table of "Part Number & Characteristic"	The rated voltage is defined as the maximum voltage, which may be applied continuously to the capacitor.				
3	Appearance		No defects or abnormalities.	Visual inspection				
4	Dimensions		Within the specified dimension.	Using calipers or Microscope.				
5	Dielectric Strengt	h (Flash)	No defects or abnormalities.	No failure shall be observed when 250% of the rated voltage is applied between the terminations for 1 to 5 seconds. The charge and discharge current is less than 50mA.				
6	Insulation Resista	ance ( I.R.)	I.R.≧10GΩ	The insulation resistance shall be measured with a DC voltage not exceeding the rated voltage at $25^{\circ}C$ and $75\%$ RH max, and within 1 minute of charging.				
7	Capacitance		Within the specified tolerance	The capacitance /Q shall be measured at $25^{\circ}$ C at the frequency and voltage shown in the tables				
8	Quality Factor ( G	1)	30pF min.: Q $\ge$ 1000 30pF max.: Q $\ge$ 400+20C C: Nominal Capacitance (pF)	Frequency 1.0±0.2MHz Voltage 1.0±0.2Vrms				
9	Capacitance Tem Characteristics	perature	Capacitance change within 0±30ppm/ °C under operating temperature range.	The capacitance value at $25^{\circ}$ C and $85^{\circ}$ C shall be measured and calculated from the formula given below. T.C.=(C <sub>85</sub> -C <sub>25</sub> )/C <sub>25</sub> * $\Delta$ T*10 <sup>6</sup> (PPM/°C)				
10	Termination Strer	ngth	No removal of the terminations or marking defect.	Apply a parallel force of 5N to a PCB mounted sample for 10±1sec. *2N for 0603 (EIA 0201).				
			No cracking or marking defects shall occur at 1mm deflection. Capacitance change: NP0: within ±5% or ± 0.5pF. (whichever is larger)	Solder the capacitor to the test jig (glass epoxy boards) shown in Fig.a using a SAC305(Sn96.5Ag3.0Cu0.5) solder. Then apply a force in the direction shown in Fig.b. The soldering shall be done with the reflow method and shall be conducted with care so that the soldering is uniform and free of defects such as heat shock.				
11	Deflection (Bending Strength)		(Unit in mm)	SNOCK. C 123 0.3 0.5 1.2 Capacitance Meter 45 Fig.b.				
12	Solderability of Te	ermination	90% of the terminations are to be soldered evenly and continuously. C0402 Series: 75% of the terminations are to be soldered evenly and continuously.	Immerse the test capacitor into a methanol solution containing rosin for 3 to 5 seconds, preheat it 150 to $180^{\circ}$ C for 2 to 3 minutes and immerse it into SAC305(Sn96.5Ag3.0Cu0.5) solder of $245 \pm 5^{\circ}$ C for 3±1seconds.				
		Appearance	No marking defects	Immerse the capacitor in a				
	Resistance to	Cap. Change	NP0 within ±2.5% or ±0.25pF ( whichever is larger )	ar ) SAC305(Sn96.5Ag3.0Cu0.5) solder solution at 270±5℃ for 10±1 seconds. Let sit at room temperature for 24±2 hours, then measure. *C0402 Series is not suitable for this testing				
13	Soldering Heat	Q	Initial spec.					
		I.R.	Initial spec.					

	lte	em	Specification	Test Method					
		Appearance Cap. Change	No marking defects NP0 within ±2.5% or 0.25pF ( whichever is larger )	Solder the capacitor to supporting jig (glass epoxy board) and perform the five cycles according to the					
	Temperature cvcle	Q	Initial spec.	four heat treatments listed in the following table. Le					
14	(Thermal shock)	I.R.	Initial spec.	Step 1: Minimum operating temperature30±3minStep 2: Room temperature2~3 minStep 3: Maximum operating temperature30±3minStep 4: Room temperature2~3min					
		Appearance	No marking defects	Apply the rated voltage at $40+2^{\circ}$ C and 90 to 95%					
15	Humidity load	Cap. Change	NP0 within $\pm 5\%$ or $\pm 0.5$ pF ( whichever is larger )	humidity for 500±12 hours. Remove and let sit fo					
15	iumany iouu	Q	200 min.	24±2 hours at room temperature, then measure.					
		I.R.	I.R.≧500MΩ	The charge / discharge current is less than 50mA.					
		Appearance	No marking defects						
		Cap. Change	NP0 within ±5% or ±0.5pF ( whichever is larger )	Apply 200% of the rated voltage for 1000+12 hours					
16	High temperature load life test	Q	30pF and over : Q $\ge$ 350 10pF and over, 30pF and below : Q $\ge$ 275+5C/2 10pF and below : Q $\ge$ 200+10C C:Nominal Capacitance(pF)	at the maximum operating temperature $\pm 3^{\circ}$ C. Let sit for 24 $\pm$ 2 hours at room temperature, then measure. The charge/discharge current is less than 50mA.					
		I.R.	$I.R. \ge 1G\Omega$						
17	7 ESR & Q		Shown in the table of "Part Number & Characteristic"	Testing frequency is shown in the table of "Part Number & Characteristic"					

MLCC

### Package

### • Tape and reel packaging

Tape and reel packaging is currently the most promising system for high-speed production. A typical 180mm (7 inch) diameter reel contains 1,500 to 15,000 capacitors, 250mm (10 inch) contains 10,000 capacitors, and 330mm (13 inch) contains 10,000 to 50,000 capacitors. Three standard sizes are available in taped and reeled package either with paper carrier tapes or embossed tapes.

### [Paper tape specifications]



SYMBOL	0603	8(0201)	<b>1005</b> (±0.0	<b>5(0402)</b> 05 mm)	<b>1608</b> (±0.1	5 <b>(0603)</b> 10 mm)	UNIT		
	SIZE	TOL.	SIZE	TOL.	SIZE	TOL.			
А	0.38	± 0.04	0.65	± 0.10	1.0	±0.2	mm		
В	0.68	± 0.04	1.15	± 0.10	1.8	±0.2	mm		
F	3.5	± 0.05	3.5	± 0.05	3.5	±0.05	mm		
Р	2	± 0.10	2	± 0.10	4	±0.1	mm		
W	8	± 0.20	8	± 0.20	8	±0.2	mm		

### [Reel specifications]



TAPE WIDTH (mm)	G (mm)	T max. (mm)	D (mm)
4	5.0 ± 1.5	8.0	180
8	10.0 ± 1.5	14.5	180
8	10.0 ± 1.5	14.5	250
8	10.0 ± 1.5	14.5	330
12	14.0 ± 1.5	18.5	180

### [Thickness and Packing Amount]

Thicknoon		Amount per reel				
THICKNESS		180 mm (7")		330 mm (13")		
Code	Spec.(mm)	Size (EIA)	Paper	Embossed	Paper	Embossed
А	0.30	0603 (0201)	15K		50K	
В	0.50	1005 (0402)	10K		50K	
D	0.80	1608 (0603)	4K		15K	

[Packing Rule]

EIA SIZE	Tape type	Reel Size	Max Reels/Box
0603 (0201)	Paper	7"	10
1005 (0402)	Paper	7"	10
1608 (0603)	Paper/Emboss	7"	10

\*Maximum 60 reels in one carton.

### Others [Storage]

- 1. The chip capacitors shall be packaged in carrier tapes or bulk cases.
- Too high temperatures or humidity may deteriorate the quality of the product rapidly. Recommended products storage with temperatures from +5℃ to +35℃, humidity from 45 to 70% RH.
- 3. The storage atmosphere must be free of gas containing sulfur and chlorine. Also, avoid exposing the product to saline moisture. If the product is exposed to such atmospheres, the terminations will oxidize and solderability will be affected.
- 4. In consideration of solderability, an allowable storage period should be within 12 months from the outgoing date of delivery. As for products in storage over 12 months, please check solderability before use.

### [Circuit Design]

- 1. Once application and assembly environments have been checked, the capacitor may be used in conformance with the rating and performance, which are provided in both the catalog and the specifications. Exceeding the specifications listed may result in inferior performance. It may also cause a short, open, smoking, or flaming to occur, etc.
- 2. Please use the capacitors in conformance with the operating temperature provided in both the catalog and the specifications. Be especially cautious not to exceed the maximum temperature. In the situation the maximum temperature set forth in both the catalog and specifications is exceeded, the capacitor's insulation resistance may deteriorate, power may suddenly surge and short-circuit may occur. The loss of capacitance will occur, and may self-heat due to equivalent series resistance when alternating electric current is passed through. As this effect becomes critical in high frequency circuits, please exercise with caution. When using the capacitor in a (self-heating) circuit, please make sure the surface of the capacitor remains under the maximum temperature for usage. Also, please make certain temperature rise remain below 20°C.
- 3. Please keep voltage under the rated voltage, which is applied to the capacitor. Also, please make certain the peak voltage remains below the rated voltage when AC voltage is super-imposed to the DC voltage. In the situation where AC or pulse voltage is employed, ensure average peak voltage does not exceed the rated voltage. Exceeding the rated voltage provided in both catalog and specifications may lead to defective withstanding voltage or, in worse case situations, may cause the capacitor to burn out.
- 4. It's is a common phenomenon of high-dielectric products to have a deteriorated amount of static electricity due to the application of DC voltage.

# MLCC

## **DARF**<br/> N

### [Handling]

Chip capacitors should be handled with care to avoid contamination or damage. The use of vacuum pick-up or plastic tweezers is recommended for manual placement. Tape and reeled packages are suitable for automatic pick and placement machine.

### [Flux]

- 1. An excessive amount of flux or too rapid temperature rise can causes solvent burst, solder can generate a large quantity of gas. The gas can spreads small solder particles to cause solder balling effect or bridging problem.
- 2. Flux containing too high of a percentage of halide may cause corrosion of termination unless sufficient cleaning is applied.
- 3. Use rosin-type flux. Highly acidic flux (halide content less than 0.2wt%) is not recommended.
- 4. The water soluble flux causes deteriorated insulation resistance between outer terminations unless sufficiently cleaned.

### [Component Spacing]

For wave soldering components, the spacing must be sufficient far apart to prevent bridging or shadowing. This is not so important for reflow process but enough space for rework should be considered. The suggested spacing for reflow soldering and wave soldering is 0.5mm and 1.0mm, respectively.

### [Solder Fillet]

Too much solder amount may increase solder stress and cause crack risk. Insufficient solder amount may reduce adhesive Strength and cause parts falling off PCB. When soldering, confirm that the solder is placed over 0.2mm of the surface of the terminations.



## **DARF**<br/> N

### [Recommended Land Pattern Dimensions]

When mounting the capacitor to substrate, it's important to consider that the amount of solder (size of fillet) used has a direct effect upon the capacitor once it's mounted.

- 1. The greater the amount of solder, the greater the stress to the elements, as this may cause the substrate to break or crack.
- 2. In the situation where two or more devices are mounted onto a common land, separate the device into exclusive pads by using soldering resist.
- 3. Land width equal to or less than component. It is permissible to reduce land width to 80% of component width.



Size mm (EIA)	L x W (mm) (Dimension tolerance)	a (mm)	b (mm)	c (mm)
0602 (0201)	0.6*0.3 (within±0.03)	0.2 to 0.35	0.2 to 0.3	0.2 to 0.4
0603 (0201)	0.6*0.3 (±0.05/±0.09)	0.2 to 0.35	0.2 to 0.35	0.25 to 0.4
4005 (0400)	1.0*0.5 (within±0.10)	0.3 to 0.5	0.35 to 0.45	0.4 to 0.6
1005 (0402)	1.0*0.5 (±0.15/±0.20)	0.4 to 0.6	0.4 to 0.5	0.5 to 0.7
4608 (0602)	1.6*0.8 (within±0.10)	0.7 to 1.0	0.6 to 0.8	0.7 to 0.8
1000 (0003)	1.6*0.8 (±0.15/±0.20/±0.25)	0.8 to 1.1	0.7 to 0.8	0.8 to 1.0

### **DARF** N

### [Resin Mold]

If a large amount of resin is used for molding the chip, cracks may occur due to contraction stress during curing. To avoid such cracks, use a low shrinkage resin. The insulation resistance of the chip will degrade due to moisture absorption. Use a low moisture absorption resin. Check carefully that the resin does not generate a decomposition gas or reaction gas during the curing process or during normal storage. Such gases may crack the chip capacitor or damage the device itself.

### [Soldering Profile for SMT Process with SnPb Solder Paste]

### **Reflow Soldering**



The difference between solder and chip surface should be controlled as following table. The rate of preheat should not exceed  $4^{\circ}$ C/sec and a target of  $2^{\circ}$ C/sec is preferred.

Chip Size	3216 and smaller	3225 and above
Preheating	∆T≦150°C	∆T≦130℃

# DARFIN

### Wave Soldering



Chip Size	3216 and smaller	3225 and above
Preheating	∆T≦150°C	-

### **Soldering Iron**



Chip Size	3216 and smaller	3225 and above
Preheating	∆T≦190°C	<b>∆T≦130</b> °C

## **DARF**<br/> N

### [Soldering]

### Reflow Soldering for Lead free (Pb free) Termination



The difference between solder and chip surface should be controlled as following table. Pre-heating is necessary for all constituents including the PCB to prevent the mechanical damages on MLCC.

The Temperature of the ramp-up rate(TL to TP) is  $3^{\circ}$ C/second max and the ramp-down Rate (TP to TL) is  $6^{\circ}$ C/second max.



### Wave Soldering for Lead free Termination

## **DARF**<br/> N

### Soldering Iron



### [Chip Layout and Breaking PCB]

1. To layout the SMD capacitors for reducing bend stress from board deflection of PCB. The following are examples of Hood and bad layout.



2. When breaking PCB, the layout should be noted that the mechanical stresses are depending on the position of capacitors. The following example shows recommendation for better design.



## **DARF** N

### [Peeling Off Force]

Peeling off force: 0.1N to 1.0  $N^*$  in the direction shown as below. The peeling speed: 300±10 mm/min



- 1. The taped tape on reel is wound clockwise. The sprocket holes are to the right as the tape is pulled toward the user.
- 2. There are minimum 150 mm as the leader and minimum 40 mm empty tape as the tail is attached to the end of the tape.